

Specification for TFT

AFR240320A0-2.2INTM

Revision V1.0





Revision History

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Contents

1.Basic Information

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) th at uses amorphous silicon TFT as a switching device. This model is composed of a T ransmissive type TFT-LCD Panel, driver circuit,back-light unit. The resolution of a 2.2' TFT-LCD contains 240X320 pixels, and can display up to 65K colors.

1.1 Features

-Low Input Voltage: 3.3V(TYP) -Display Colors of TFT LCD: 65K colors Interface: 8/16Bit MCU Interface

General Information	Specification	Unit	Note
Items	Main Panel		Note
Display area(AA)	33.84(H) *45.12(V) (2.2inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K	colors	-
Number of pixels	240(RGB)*320	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.141 (H) x 0.141 (V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ER61516	-	-
Display mode	Normally Black	-	-
Operating temperature	-20~+70	°C	-
Storage temperature	-30~+80	°C	-

1.2 Mechanical Information

	ltem	Min.	Тур.	Max.	Unit	Note
	Horizontal(H)		41.70		mm	-
Module size	Vertical(V)		56.16		mm	-
0.20	Depth(D)			2.6	mm	-
	Weight		TBD		g	-

2.Block Diagram



3.Outline Dimension



4. Input terminal Pin Assignment

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	Р
2	XR	Touch panel Right Glass Terminal	A/D
3	YD	Touch panel Bottom Film Terminal	A/D
4	XL	Touch panel LEFT Glass Terminal	A/D
5	YU	Touch panel Top Film Terminal	A/D
6	NC		
7	NC		
8	NC		
9	IMO	Interface select signal. IMO Interface type DB Pin in use 0 DBI Tyb_ 16-bit interface DB15-DB0 1 DBI Tyb_ 8-bit interface DB7-DB0	I
10	RESET	Reset pin. The R61516 is initialized when RESX is Low. Make sure to execute power-on reset when turning the power supply on.	I
11-16	NC		
17-32	DB15-DB0	16-bit bi-directional data bus in DBI Type B operation.	I/O
33	CS	Chip select signal. Low: Select (Accessible) High: Not select (Inaccessible) Make sure to connect to host processor. Follow AC timing to control the signal.	I
34	RS	Command/data select signal Low: Select command High: Select data	I
35	WR	Write strobe signal in DBI Type B operation. Write data when WRX is Low.	I
36	RD	Read strobe signal. Read out data when RDX is Low.	

37-38	NC		
39	IOVCC	Supply voltage(1.65-3.3V).	Р
40	VCC	Supply voltage(3.3V).	Р
41	LEDK	Cathode pin OF backlight	Ρ
42	LEDA1	Anode pin of backlight	Ρ
43	LEDA2	Anode pin of backlight	Р
44	LEDA3	Anode pin of backlight	Р
45	GND	Ground.	Р

5.LCD Optical Characteristics

5.1 Optical Specification

ltem		Symbol	Condition	Min.	Тур.	Max.	Unit.	Note
Contrast R	Ratio	CR	Θ=0		500			
Response	Rising		Normal					
time	Falling	$T_{R+}T_{F}$	viewing		35	50	msec	Fig.3
	ranng		angle					
Color gar	nut	S(%)			75		%	
		Wx		0.287	0.327	0.367		
	White	W _Y		0.317	0.357	0.397		
	Red	Rx		0.611	0.631	0.651		
Color Filter		Ry		0.318	0.338	0.358		
Chromacicity	Green	Gx		0.313	0.333	0.353		
		G _Y		0.595	0.615	0.635		
		Bx		0.13	0.15	0.17		
	Blue	B _Y		0.024	0.044	0.064		
		Θι			80			
Viewing angle	Hor.	Θr			80			C/R>10
		Θυ	CR>10		80			Fig.4
	Ver.	ΘD			80			
Option View D	Direction			Free				

Notes : 1. Contrast Ratio(CR) is defined mathematically as :

Surface Luminance with all white pixels

Contrast Ratio =

Surface Luminance with all black pixels

- Surface luminance is the center point across the TFT-LCD surface 500 mm from the surface with all pixels displaying white. For more information see FIG 1.
- Response time is the time required for the display to transition from white to black(Rise Time, Tr) and from black to white(Falling Time, Tf). For additional information see FIG 3.
- 4. Viewing angle is the angle at which the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the TFT-LCD surface. For more information see FIG 4.
- 5. Optimum contrast is obtained by adjusting the TFT-LCD Threshold voltage(Vth & Vsat)

FIG. 1 Optical Characteristic Measurement Equipment and Method





Light Source



<Transmissive Mode>

FIG. 2 The definition of Vth and Vsat



FIG. 3 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".



* Voltage conditions for Response time Vgate : 22V DC Vdata : 0V~4.5V DC Vcom : 0V (Ground)

FIG. 4 The definition of viewing angle

<dimension of viewing angle range>



6.Electrical Characteristics

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VCC	-0.3	4.6	V
Supply Voltage (Logic)	IOVCC	-0.3	4.6	
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	Tst	-30	+80	°C

6.1 Absolute Maximum Rating (Ta=25 VSS=0V)

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	VCC	2.5	3.3	3.6	V	
Supply Voltage (Logic)	IOVCC	1.65	1.8	3.3		
Normal mode Current consumption	IDD		9		mA	
Level input voltage	Vін	0.7 IOVCC		IOVCC	V	
	VIL	GND		0.3 IOVCC	V	
Level output voltage	Vон	0.8 IOVCC		IOVCC	V	
	Vol	GND		0.2 IOVCC	V	

6.2 DC Electrical Characteristics

6.3 LED Backlight Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Note
Forward Current	lF	45	60		mA	
Forward Voltage	VF		3.2		V	
LCM Luminance	Lv		450		cd/m2	Note3
LED life time	Hr	50000			Hour	Note1,2
Uniformity	AVg	80			%	Note3

The back-light system is edge-lighting type with 3 chips White LED

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=60mA. The LED lifetime could be decreased if operating IL is larger than 60mA. The constant current driving method is suggested.





NOTE 3: Luminance Uniformity of these 9 points is defined as below:

7.AC Characteristic



7.1 8080 Series MCU Parallel Interface Characteristics: 16/8-bit Bus

Figure A DBI Type B (16-/ 18- bit, 8-/9- bit timing) Bus Timing

Note 1: Logic High and Low levels of input signals are defined as follows: RESX: IOVCC x 10%, 90% Other than RESX: IOVCC x 20%, 80% Note 2: Unused DB[17:0] pins shall be fixed at "IOVCC" or "GND".

ltem	Symbol	、 · ·	Unit	Test Condition	Min.	Max.
Address setup time	DCX	tast	ns		0	-
Address hold time (Write/Read)		taht	ns		10	-
Chip select setup time (Write)		tcs	ns		20	-
Chip select setup time (Read)	CSX	trcs	ns		170	-
Chip select wait time (Write/Read)	1	tcsf	ns		20	-
Write cycle time (Normal Write / High- speed write)		twc	ns		100/80	-
Write control pulse "High" period	WRX	twrh	ns		35	-
Write control pulse "Low" period		twrl	ns		35	-
Read cycle time		trc	ns		450	-
Read control pulse "High" period	RDX	trdh	ns		250	-
Read control pulse "Low" period	1	trdl	ns		170	-
Write data setup time		twds	ns	CL	15	-
dress hold time (Write/Read) ip select setup time (Write) ip select setup time (Read) ip select wait time (Write/Read) ite cycle time (Normal Write / High- eed write) ite control pulse "High" period ite control pulse "Low" period ad cycle time ad control pulse "Low" period ite data setup time ite data hold time ad access time tiput disable time	DB[17:0]	twdh	ns		25	-
Read access time		tracc	ns	Max.30pF Min.8pF	10	340
Output disable time	1	trod	ns	мп.орг	10	-
Rise / Fall time	-	tr/tf	ns		-	15

7.2 Reset Timing

Item	Symbol	Unit	Test Condition	Min.	Max.
Reset "Low" level width	tRW	us	Power On	10	-
Reset Time	tRT	ms		<u> </u>	5



Figure D Reset Timing

8.LCD Module Out-Going Quality Level

8.1 VISUAL & FUNCTION INSPECTION STANDARD

8.1.1 Inspection conditions



8.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen) Zone B : Viewing Area except Zone A Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .) Zone D : IC Bonding Area

Note:As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

8.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class $\,\rm II\,$ AQL:

Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display, TP: Touch Panel, LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	 No display, Open or miss line Display abnormally, Short Backlight no lighting, abnormal lighting. TP no function 	Major
2	Missing	Missing component	Major
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	
5	Light dot, Dim spot,Polarizer		Minor
6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

8.1.4 Criteria (Visual)

Number	Items	Criteria(mm)			
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of	(1) The edge of LCD broken				
ITO, T: Height of	DIOKEII	Х	Y	Z	
LCD		≤3.0mm	<inner border="" lir<br="">the seal</inner>	ne of _≤T	
	(2)LCD corner broken	X _≤3.0mr	Y n ≤L	Z ≤T	
	(3) LCD crack Crack Not allowed		Crack Not allowed		

	Spot defect	① light dot(LCD pinhole, dent, sta		black/white	spot ,	light dot,
		Zone		Acceptable Q	ty	
		Size (mm)	А	В		С
2.0		Ф≤0.10	Ign	ore		
	I⊲ → X	0.10<Φ≤0.20	3(distance	e≧10mm)	1.	
	Φ=(X+Y)/2	0.20<Φ≤0.25	0.20<Φ≤0.25 2		- Ignore	
	. (,	Φ>0.3	0			
		②Dim spot(LCI dark spot)	D/TP/Polarize	er dim dot, li	ght le	akage、
		Zone	A	cceptable Q	ty	
		Size (mm)	А	В		С
		Ф≤0.1	Ign	ore		
		0.10<Φ≤0.20	3(distance	e≧10mm)		gnore
		0.20<Φ≤0.25	2			
		Φ>0.3	C)		
		③ Polarizer accidented spot				
		Zone Size (mm)	Acceptable Q			•
			A	B		С
		Φ≤0.2	Ignore			
		0.3<Φ≤0.5		æ≧10mm)	I	gnore
		Φ>0.5		0		
		④Pixel bad point	s(light dot,	Dim dot, col	or do)
		Zone	ŀ	Acceptable C	(ty	
		Size (mm)	ŀ	4	В	С
		Ф≤0.1	lgn	ore		
		0.15<Φ≤0.2	2(distance	e≧10mm)	IÇ	Inore
		Φ>0.2	()		
		5 Polarizer Bubb	le			
		Zone Acceptable Qty				
		Size (mm)	Size (mm) A B			С
		Ф≤0.2	lgn	ore		
		0.3<Φ≤0.4	3(distance≧10mm		1.	
		0.4<Φ≤0.5	2		ıç	Inore
		Φ>0.5	(0		

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		(Midth (mm)	Longth (mm)	Acceptable Qty		
	Line defect	Width(mm)	Length(mm)	А	В	С
	(LCD/TP /Polarizer	Ф≤0.03	Ignore	lgnor	e	
3.0	backlight black/white	0.03 <w≤0.04< td=""><td>L≤3.0</td><td>N≤2</td><td></td><td>Ignore</td></w≤0.04<>	L≤3.0	N≤2		Ignore
	line, scratch,	0.04 <w≤0.05< td=""><td>L≤2.0</td><td>N≤1</td><td></td><td></td></w≤0.05<>	L≤2.0	N≤1		
	stain)	0.05 <w< td=""><td>Defi</td><td>ne as spot</td><td>defect</td><td></td></w<>	Defi	ne as spot	defect	
4.0	Electronic Co m p o n e n t s SMT	Not allow missing parts,solderless connection,cold solder jo int,mismatch,The positive and negative polarity opposite				,
5.0	Display color					
5.0	& Brightness	 Brightness: Measuring the brightness of White scree e measurement standard according to the datasheet mples. 				

			Size Φ(mm)	Size $\Phi(mm)$ Acceptabl		ty		
		TP film		A	В		С	
		bubble/	Ф≤0.1	Igno	re			
		accidented spot	0.1<Ф≤0.2	3 (dista	nce≧	Ι.		
6.0	RTP		0.25<Ф≤0.3	2			Ignore	
0.0	Related		Φ>0.3	0		-		
				•				
			Width(mm)	lth(mm)		eptable Qty		
				Lengan(min)	А	В	С	
			Ф≤0.03	Ignore	Ignore			
		TP film scratch	0.03 <w≤0.04< td=""><td>L≤3.0</td><td>N≤2</td><td></td><td>Ignore</td></w≤0.04<>	L≤3.0	N≤2		Ignore	
		Scraton	0.04 <w≤0.05< td=""><td>L≤2.0</td><td>N≤1</td><td colspan="2"></td></w≤0.05<>	L≤2.0	N≤1			
			0.05 <w< td=""><td colspan="2">Define as spot defect</td><td>t</td></w<>	Define as spot defect		t		
		Assembly deflection	beyond the edge of backlight ≤0.2mm				1	



TP edge	X X≤ 4mm	Y Y≤ 2mm	Z Z <cover< b=""> thickness</cover<>	
TP edge broken X : length Y : width Z : height	* Circi allowe		roken is not	Z

Criteria (functional items)

		• · · · / · ·
Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

9. Reliability Test Result

ltem	Condition	Inspection after
		test
High Temperature Operating	70℃,96H	
Low Temperature Operating	-20℃, 96HR	Inspection after
High Temperature Storage	80°C, 96HR	2~4hours storage
Low Temperature Storage	-30℃, 96HR	at room
High Temperature & High Humidity Storage	+60 ℃, 90% RH ,96 hours.	temperature, the sample shall be
Thermal Shock (Non-	-30 °C ,30 min ↔ 80 °C ,30 min, Change	free from defects:
operation)	time:5min 20CYC.	1.Air bubble in
	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15℃~35℃, 30%~60%).	the LCD; 2.Non-display; 3.Missing segments/line;
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	-4.Glass crack; 5.Current IDD is twice higher than initial value.
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

Remark:

1. The test samples should be applied to only one test item.

2.Sample size for each test item is 5~10pcs.

3.For Damp Proof Test, Pure water(Resistance > 10M Ω) should be used.

4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

10. Cautions and Handling Precautions

10.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.

(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.

(4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.

(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth.

In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.

(8) Protect the module from static; it may cause damage to the CMOS ICs.

(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.

(10) Do not disassemble the module.

(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.

(12) Pins of I/F connector shall not be touched directly with bare hands.

(13) Do not connect, disconnect the module in the "Power ON" condition.

(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

10.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.

It is highly recommended to store the module with temperature from 0 to 35 $^\circ\!\!C$ and relative humidity of less than 70%

(2) Do not store the TFT-LCD module in direct sunlight.

(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.

(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.

In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.

(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

11. Packing

